Taiwan Semiconductor

# 8A, 45V Trench Schottky Rectifiers

# FEATURES

• AEC-Q101 qualified

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- Patented Trench Schottky technology
- Low power loss, high efficiency
- Ideal for automated placement
- Wettable flank
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

# APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- On-board DC/DC converter
- Automotive

# MECHANICAL DATA

- Case: SMPC4.6U
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 104mg (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
I <sub>F</sub>	8	А
V <sub>RRM</sub>	45	V
I <sub>FSM</sub>	150	А
T <sub>J MAX</sub>	175	°C
Package	SMPC4.6U	



SMPC4.6U



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER		SYMBOL	TSUP8M45SH	UNIT
Marking code on the device			8M45	
Repetitive peak reverse voltage		V <sub>RRM</sub>	45	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	32	V
Forward current		I <sub>F</sub>	8	А
Surge peak forward current single	8.3 ms at T <sub>A</sub> = 25°C		150	^
half sine-wave superimposed on rated load	1.0 ms at T <sub>A</sub> = 25°C	I <sub>FSM</sub>	286	A
Junction temperature		TJ	-55 to +175	°C
Storage temperature		T <sub>STG</sub>	-55 to +175	°C





THERMAL PERFORMANCE			
PARAMETER	SYMBOL	ТҮР	UNIT
Junction-to-lead thermal resistance	R <sub>ƏJL</sub>	7	°C/W
Junction-to-ambient thermal resistance	R <sub>ƏJA</sub>	56	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	12	°C/W

Thermal Performance Note: Units mounted on PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS ( $T_A = 25^{\circ}C$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage <sup>(1)</sup>	$I_F = 4.0A, T_J = 25^{\circ}C$	V <sub>F</sub>	0.48	-	V
	$I_F = 8.0A, T_J = 25^{\circ}C$		0.54	0.60	V
	$I_F = 4.0A, T_J = 125^{\circ}C$		0.38	-	V
	$I_F = 8.0A, T_J = 125^{\circ}C$		0.46	0.54	V
Reverse current @ rated $V_R^{(2)}$	$T_J = 25^{\circ}C$	I <sub>R</sub>	-	200	μA
	T <sub>J</sub> = 125°C		-	8	mA
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	932	-	pF

#### Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

ORDERING INFORMATION		
ORDERING CODE	PACKAGE	PACKING
TSUP8M45SH M3G	SMPC4.6U	1,500/7" reel
TSUP8M45SH M2G	SMPC4.6U	6,000/13" reel



# **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

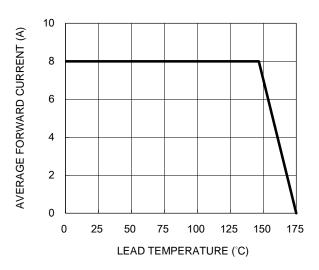
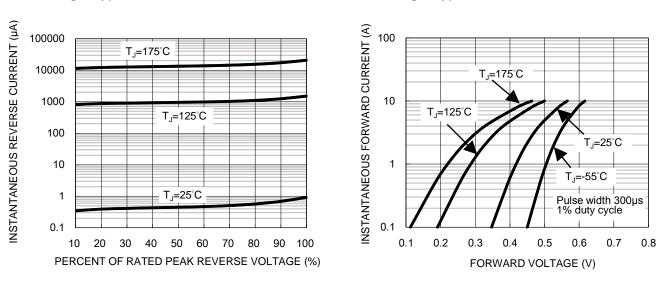
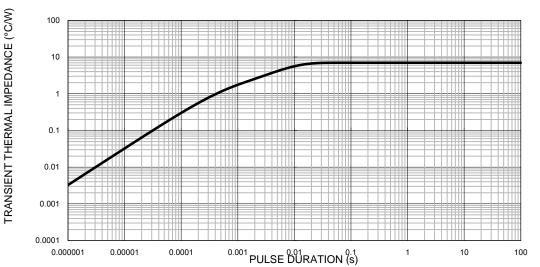


Fig.1 Forward Current Derating Curve

#### Fig.3 Typical Reverse Characteristics





# Fig.5 Typical Transient Thermal Impedance

Fig.2 Typical Junction Capacitance

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**REVERSE VOLTAGE (V)** 

**Fig.4 Typical Forward Characteristics** 

100

10000.0

1000.0

100.0

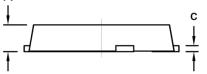
1

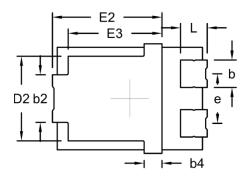
f=1.0MHz Vsig=50mVp-p

CAPACITANCE (pF)

## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

Е Μ ł N D D1 E1 L1 А





SUGGESTED PAD LAYOUT

В

D

F

1

С

1

DIM.	Unit (mm)		Unit (	inch)
DIN.	Min.	Max.	Min.	Max.
А	1.00	1.20	0.039	0.047
b	1.05	1.35	0.041	0.053
b2	1.90	2.20	0.075	0.087
b4	0.75 (	NOM.)	0.030	(NOM.)
с	0.15	0.40	0.006	0.016
D	4.45	4.75	0.175	0.187
D1	4.25	4.35	0.167	0.171
D2	3.40	3.70	0.134	0.146
E	6.35	6.65	0.250	0.262
E1	6.05	6.15	0.238	0.242
E2	4.40	4.80	0.173	0.189
E3	3.94 (NOM.)		0.155	(NOM.)
е	2.08 (NOM.)		0.082	(NOM.)
L	0.94	1.24	0.037	0.049
L1	0.05	0.35	0.002	0.014
М	0.65	1.15	0.026	0.045
Ν	0.25	0.75	0.010	0.030

Package body size D1 and E1 do not include mold flash Mold flash shall not exceed 0.1mm per side

Symbol	Unit (mm)	Unit (inch)
A	4.95	0.195
В	4.95	0.195
С	1.60	0.063
D	1.42	0.056
E	6.95	0.274
F	1.04	0.041

### **MARKING DIAGRAM**

А

1



- E

P/N	= Marking Code
YW	= Date Code
F	= Factory Code

Version:A2003

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